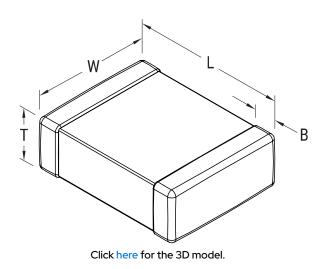




CBR-SMD RF COG, Ceramic, 6.8 pF, +/-0.1 pF, 50 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0402



General Information	
Series	CBR-SMD RF COG
Style	SMD Chip
Description	SMD, Fixed, RF, Ultra High Q, Low ESR, Class I
Features	Ultra High Q, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	1.37 mg
Notes	Solder Reflow Only.
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	0402
L	1mm +/-0.05mm
W	0.5mm +/-0.05mm
Т	0.5mm +/-0.05mm
В	0.25mm +0.05/-0.1mm

Т	0.5mm +/-0.05mm	Dielectric Withstanding Voltage	125 V
В	0.25mm +0.05/-0.1mm	Temperature Range	-55/
		Temp. Coefficient	COG
Packaging Specifications		Dissipation Factor	0.187
Packaging	T&R, 180mm, Plastic Tape	Aging Rate	0% L
Packaging Quantity	10000	Insulation Resistance	10 G

Specifications	
Capacitance	6.8 pF
Tolerance	+/-0.1 pF
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Dissipation Factor	0.187%
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	10 GOhms
Quality Factor	536

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